- **Extended Temperature Performance of –40°C to 125°C**
- **Optimized for Off-line and DC to DC Converters**
- **Low Start Up Current (<0.5 mA)**
- **Trimmed Oscillator Discharge Current**
- **Automatic Feed Forward Compensation**
- **Pulse-by-Pulse Current Limiting**
- **Enhanced Load Response Characteristics**
- **Under-Voltage Lockout With Hysteresis**
- **Double Pulse Suppression**
- **High Current Totem Pole Output**
- **Internally Trimmed Bandgap Reference**
- **500 kHz Operation**
- **Low R_O Error Amp**

D 8-PIN PACKAGE
(TOP VIEW)

COMP	1	8 V_{REF}
V_{FB}	2	7 V_{CC}
I_{SENSE}	3	6 OUTPUT
R_T/C_T	4	5 GND

D 14-PIN PACKAGE
(TOP VIEW)

COMP	1	14 V_{REF}
NC	2	13 NC
V_{FB}	3	12 V_{CC}
NC	4	11 V_C
I_{SENSE}	5	10 OUTPUT
NC	6	9 GND
R_T/C_T	7	8 PWR GND
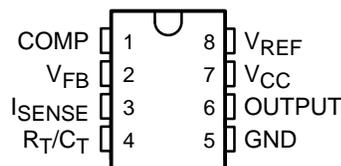
description

The UC2842A/3A/4A/5A family of control ICs is a pin for pin compatible improved version of the UC2842/3/4/5 family. Providing the necessary features to control current mode switched mode power supplies, this family has the following improved features. Start up current is guaranteed to be less than 0.5 mA. Oscillator discharge is trimmed to 8.3 mA. During under voltage lockout, the output stage can sink at least 10 mA at less than 1.2 V for V_{CC} over 5 V.

The difference between members of this family are shown in the table below.

PART NUMBER	UVLO ON	UVLO OFF	MAXIMUM DUTY CYCLE
UC2842A	16 V	10 V	<100%
UC2843A	8.5 V	7.9 V	<100%
UC2844A	16 V	10 V	<50%
UC2845A	8.5 V	7.9 V	<50%

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TEXAS INSTRUMENTS

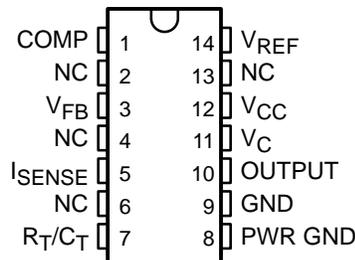# UC2842AQ, UC2843AQ, UC2844AQ, UC2845AQ
CURRENT-MODE PWM CONTROLLER

SGLS164 – APRIL 2003

ORDERING INFORMATION†

T$_A$	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 125°C	SOIC-8 – D8	Tape and reel	UC2842AQD8R	2842AQ
	SOIC-8 – D8	Tube	UC2842AQD8	2842AQ
	SOIC-14 – D	Tape and reel	UC2842AQDR	2842AQ
	SOIC-14 – D	Tube	UC2842AQD	2842AQ
	SOIC-8 – D8	Tape and reel	UC2843AQD8R	2843AQ
	SOIC-8 – D8	Tube	UC2843AQD8	2843AQ
	SOIC-14 – D	Tape and reel	UC2843AQDR	2843AQ
	SOIC-14 – D	Tube	UC2843AQD	2843AQ
	SOIC-8 – D8	Tape and reel	UC2844AQD8R	2844AQ
	SOIC-8 – D8	Tube	UC2844AQD8	2844AQ
	SOIC-14 – D	Tape and reel	UC2844AQDR	2844AQ
	SOIC-14 – D	Tube	UC2844AQD	2844AQ
	SOIC-8 – D8	Tape and reel	UC2845AQD8R	2845AQ
	SOIC-8 – D8	Tube	UC2845AQD8	2845AQ
	SOIC-14 – D	Tape and reel	UC2845AQDR	2845AQ
	SOIC-14 – D	Tube	UC2845AQD	2845AQ

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

block diagram

NOTES: 1. A = DIL-8 Pin Number. B = SO-14 Pin Number.
2. Toggle flip flop used only in 2844A and 2845A.
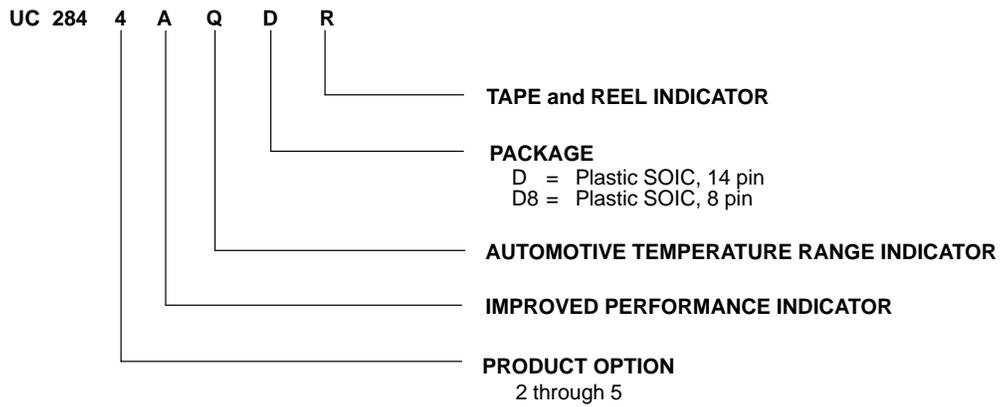
Ordering Information

UC 284 4 A Q D R

TAPE and REEL INDICATOR

PACKAGE
  D = Plastic SOIC, 14 pin
  D8 = Plastic SOIC, 8 pin

AUTOMOTIVE TEMPERATURE RANGE INDICATOR

IMPROVED PERFORMANCE INDICATOR

PRODUCT OPTION
  2 through 5

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†‡

V_{CC} voltage (low impedance source) . . . . 30 V
V_{CC} voltage (I_{CC} mA) . . . . self limiting
Output current, I_O . . . . ±1 A
Output energy (capacitive load) . . . . 5 µJ
Analog Inputs (pins 3, 5) . . . . –0.3 V to 6.3 V
Error Amp Output Sink current . . . . 10 mA
Power Dissipation at T_A < +25°C (D package) . . . . 1 W
Package thermal impedance, θ_{JA} (see Note 1): D (8-pin) package . . . . 97°C/W
Storage temperature range, T_{stg} . . . . –65°C to 150°C
Lead temperature soldering 1,6 mm (1/16 inch) from case for 10 seconds . . . . 260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

‡ Unless otherwise indicated, voltages are reference to ground and currents are positive into and negative out of the specified terminals.

NOTE 1: Long term high–temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

electrical characteristics, T_A = –40°C to 125°C, V_{CC} = 15 V (see Note 1), R_T = 10 kΩ, C_T = 3.3 nF, and T_A = T_J (unless otherwise stated)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Reference Section						
Output voltage	T_J = 25°C, I_O = 1 mA		4.95	5.0	5.05	V
Line regulation voltage	V_{IN} = 12 V to 25 V			6	20	mV
Load regulation voltage	I_O = 1 mA to 20 mA			6	25	mV
Temperature stability	See Notes 2 and 3			0.2	0.4	mV/°C
Total output variation voltage	Line, Load, Temp.		4.9		5.1	V
Output noise voltage	f = 10 Hz to 10 kHz, See Note 2	T_J = 25°C		50		µV
Long term stability	1000 hours, See Note 2	T_A = 125°C		5	25	mV
Output short-circuit current			–30	–100	–180	mA
Oscillator Section						
Initial accuracy	See Note 4	T_J = 25°C	47	52	57	kHz
Voltage stability	V_{CC} = 12 V to 25 V			0.2	1	%
Temperature stability	T_A = MIN to MAX, See Note 2			5		%
Amplitude peak-to-peak	V pin 7, See Note 2			1.7		V
Discharge current	V pin 7 = 2 V, See Note 5	T_J = 25°C	7.8	8.3	8.8	mA
		T_J = Full range	7.5		8.8	

electrical characteristics, T_A = −40°C to 125°C, V_{CC} = 15 V (see Note 1), R_T = 10 kΩ, C_T = 3.3 nF, and T_A = T_J (unless otherwise stated)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Error Amplifier Section						
Input voltage	COMP = 2.5 V		2.45	2.5	2.55	V
Input bias current				−0.3	−1	µA
Open loop voltage gain (A_{VOL})	V_O = 2 V to 4 V		65	90		dB
Unity gain bandwidth	See Note 2	T_J = 25°C	0.7	1		MHz
PSRR	V_{CC} = 12 V to 25 V		60	70		dB
Output sink current	FB = 2.7 V, COMP = 1.1 V		2	6		mA
Output source current	FB = 2.3 V, COMP = 5 V		−0.5	−0.8		mA
V_{OUT} high	FB = 2.3 V, R_L = 15 kΩ to GND		5	6		V
V_{OUT} low	FB = 2.7 V, R_L = 15 kΩ to V_{REF}			0.7	1.1	V
Current Sense Section						
Gain	See Notes 6 and 7		2.85	3	3.15	V/V
Maximum input signal	COMP = 5 V, See Note 6		0.9	1	1.1	V
PSRR	V_{CC} = 12 V to 25 V, See Note 6			70		dB
Input bias current				−2	−10	µA
Delay to output	I_{SENSE} = 0 V to 2 V, See Note 2			150	300	ns
Output Section (OUT)						
Low-level output voltage	I_{OUT} = 20 mA			0.1	0.4	V
	I_{OUT} = 200 mA			15	2.2	
High-level output voltage	I_{OUT} = −20 mA		13	13.5		V
	I_{OUT} = −200 mA		12	13.5		
Rise time	C_L = 1 nF, See Note 2	T_J = 25°C		50	150	ns
Fall time	C_L = 1 nF, See Note 2	T_J = 25°C		50	150	ns
UVLO saturation	V_{CC} = 5 V, I_{OUT} = 10 mA			0.7	1.2	V
Undervoltage Lockout Section						
Start threshold		UC2842A, UC2844A	15	16	17	V
		UC2843A, UC2845A	7.8	8.4	9	
Minimum operation voltage after turn on		UC2842A, UC2844A	9	10	11	V
		UC2843A, UC2845A	7	7.6	8.2	

electrical characteristics, T_A = –40°C to 125°C, V_{CC} = 15 V (see Note 1), R_T = 10 kΩ, C_T = 3.3 nF, and T_A = T_J (unless otherwise stated)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNITS
PWM Section						
Maximum duty cycle		UC2842A, UC2843A	94	96	100	%
		UC2844A, UC2845A	47	48	50	
Minimum duty cycle					0	%
Total Standby Current						
Start-up current				0.3	0.5	mA
Operating supply current	FB = 0 V, SENSE = 0 V			11	17	mA
V_{CC} internal zener voltage	I_{CC} = 25 mA		30	34		V

NOTES: 1. Adjust V_{CC} above the start threshold before setting at 15 V.
2. Not production tested.
3. Temperature stability, sometimes referred to as average temperature coefficient, is described by the equation:

$$\text{Temp Stability} = \frac{V_{REF}(\text{max}) - V_{REF}(\text{min})}{T_J(\text{max}) - T_J(\text{min})}. \; V_{REF}(\text{max}) \text{ and } V_{REF}(\text{min}) \text{ are the maximum and minimum reference voltage measured}$$

over the appropriate temperature range. Note that the extremes in voltage do not necessarily occur at the extremes in temperature.
4. Output frequency equals oscillator frequency for the UC2842A and UC2843A. Output frequency is one half oscillator frequency for the UC2844A and UC2845A.
5. This parameter is measured with R_T = 10 kΩ to V_{REF}. This contributes approximately 300 μA of current to the measurement. The total current flowing into the $R_{T/C}$ pin will be approximately 300 μA higher than the measured value.
6. Parameter measured at trip point of latch with V_{FB} at 0 V.
7. Gain is defined by: $A = \dfrac{\Delta V_{COMP}}{\Delta V_{SENSE}}$; $0 \leq V_{SENSE} \leq 0.8$ V.

PA

RAMETER MEASUREMENT INFORMATION
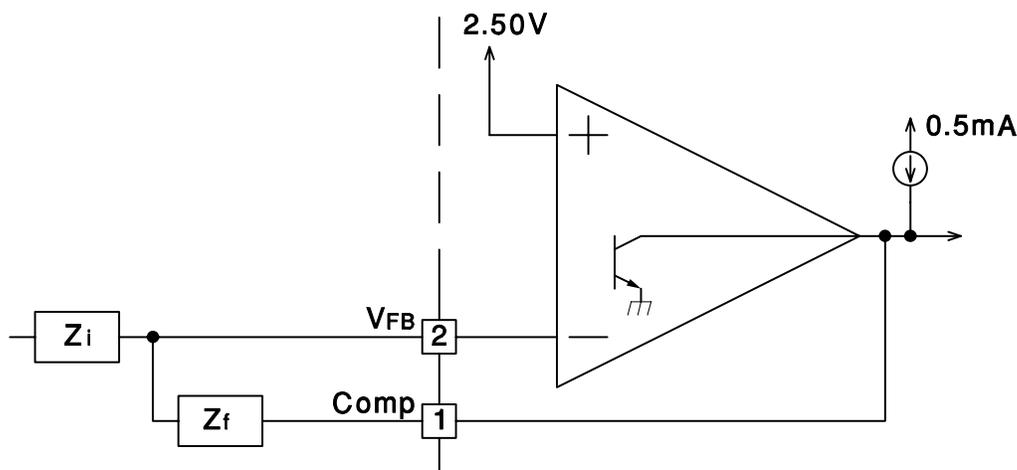
Error Amp can source and sink up to 0.5 mA, and sink up to 2 mA.

Figure 1. Error Amp Configuration
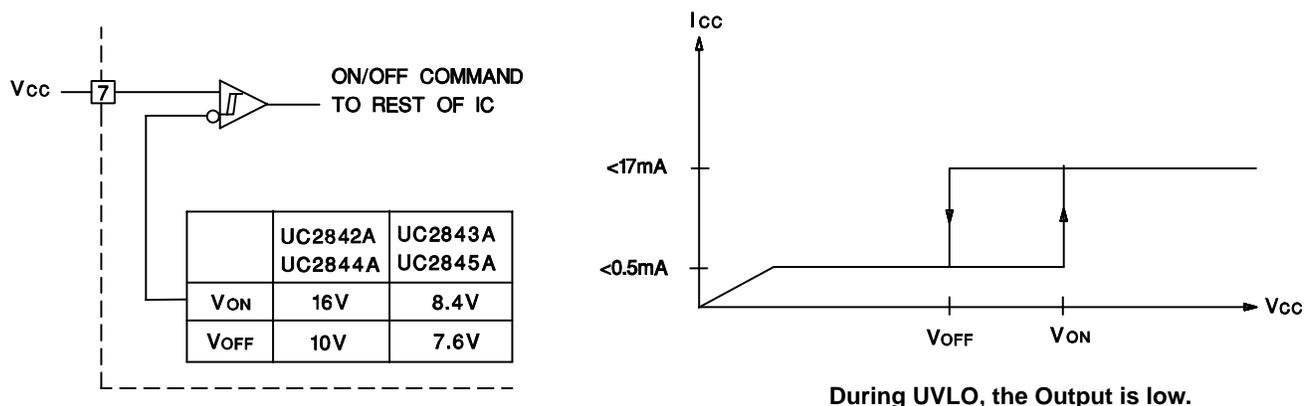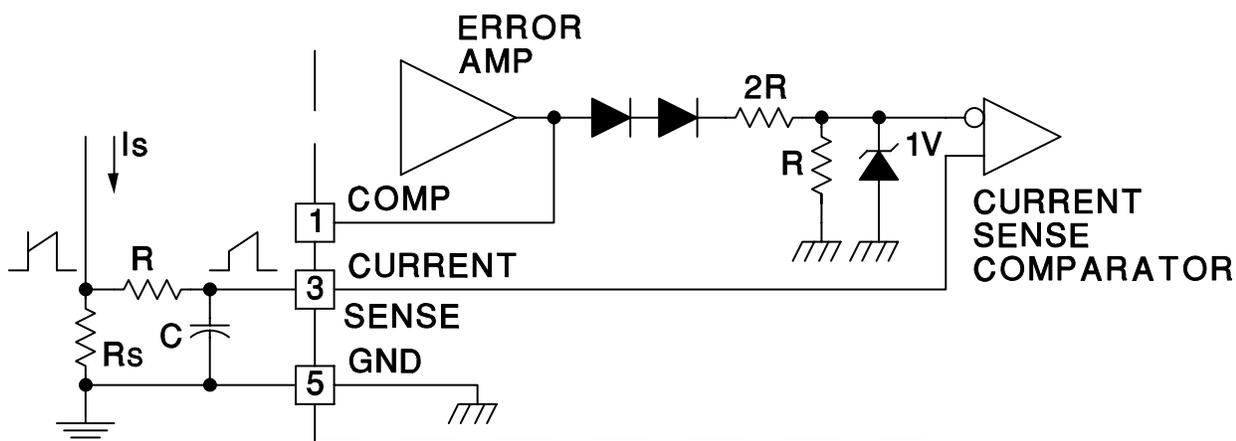
PARAMETER MEASUREMENT INFORMATION

	UC2842A UC2844A	UC2843A UC2845A
V$_{ON}$	16V	8.4V
V$_{OFF}$	10V	7.6V

During UVLO, the Output is low.

Figure 2. Under Voltage Lockout

Peak Current (Is) is Determined By The Formula:

$$\text{Ismax}' \frac{1.0V}{RS}$$

A small RC filter may be required to supress switch transients.

Figure 3. Current Sense Circuit

PARAMETER MEASUREMENT INFORMATION

Output Saturation Characteristics

V_{CC} = 15V
T_A = +25°C ——
T_A = -55°C – –

SOURCE SAT ($V_{CC}-V_{OH}$)
SINK SAT (V_{OL})

Figure 4

Error Amplifier Open-Loop Frequency Response

ϕ
A_V
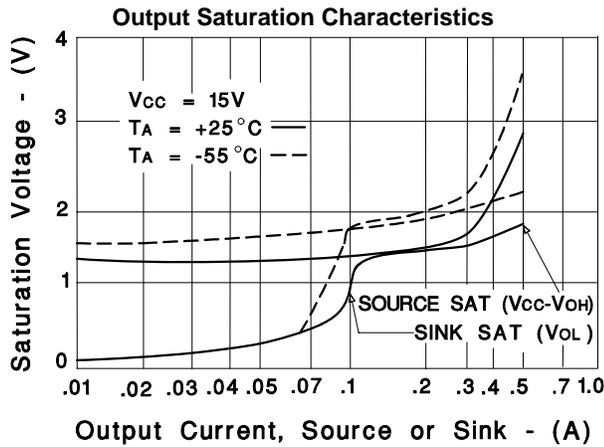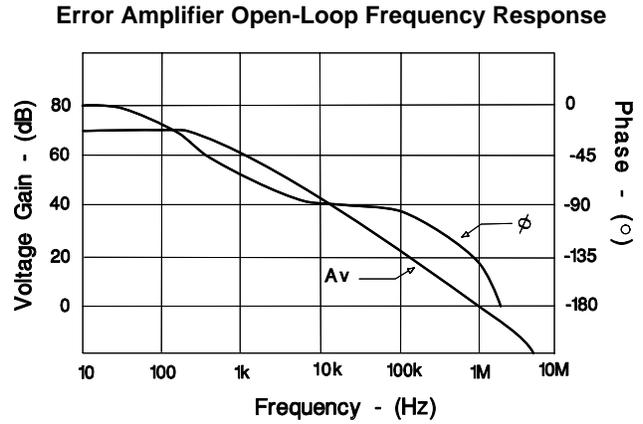
Figure 5

AP

PLICATION INFORMATION

VREF 8
RT/CT 4
GROUND 5
RT
CT

For $R_T > 5k$ $f \approx \dfrac{1.72}{R_T C_T}$

Oscillator Frequency vs Timing Resistance

C_T=470pF
1nF
2.2nF
4.7nF

Maximum Duty Cycle vs Timing Resistor

Figure 6. Oscillator
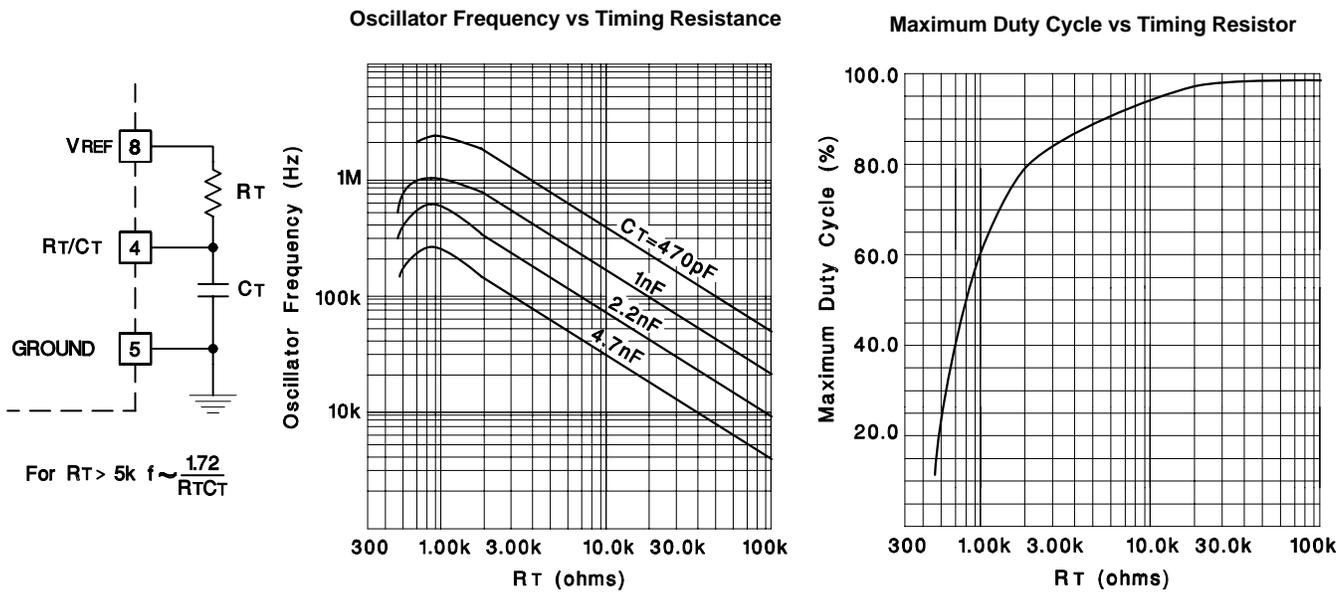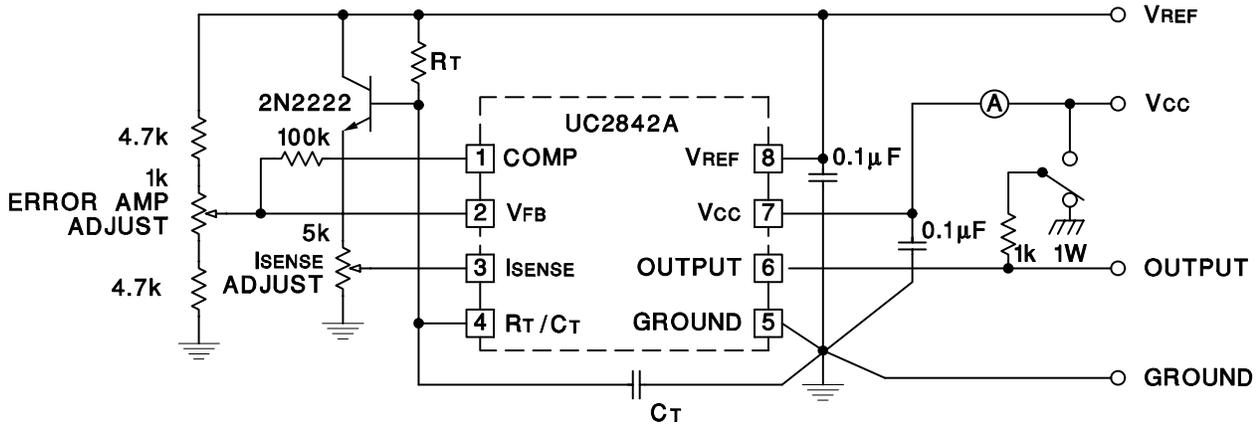
TEXAS
INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

APPLICATION INFORMATION

High peak currents associated with capacitive loads necessitate careful grounding techniques. Timing and bypass capacitors should be connected close to pin 5 in a single point ground. The transistor and 5k potentiometer are used to sample the oscillator waveform and apply an adjustable ramp to pin 3.

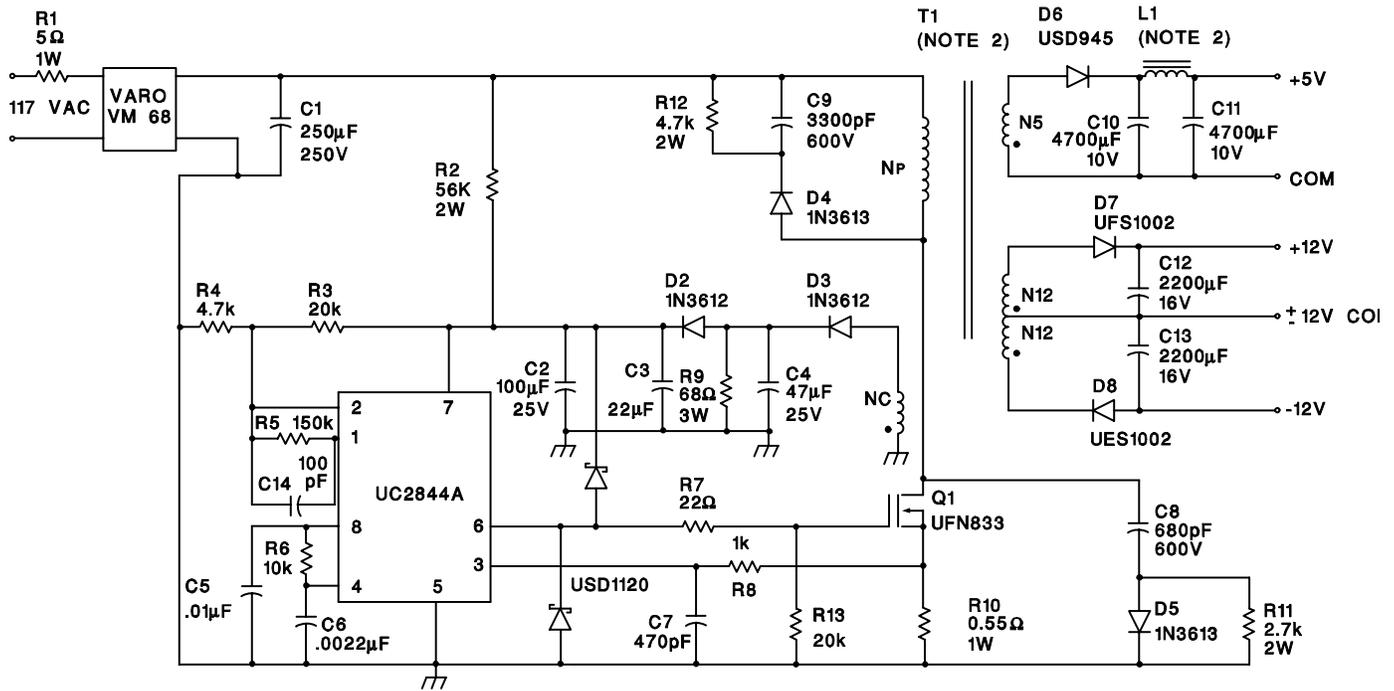**Figure 7. Open-Loop Laboratory Text Fixture**
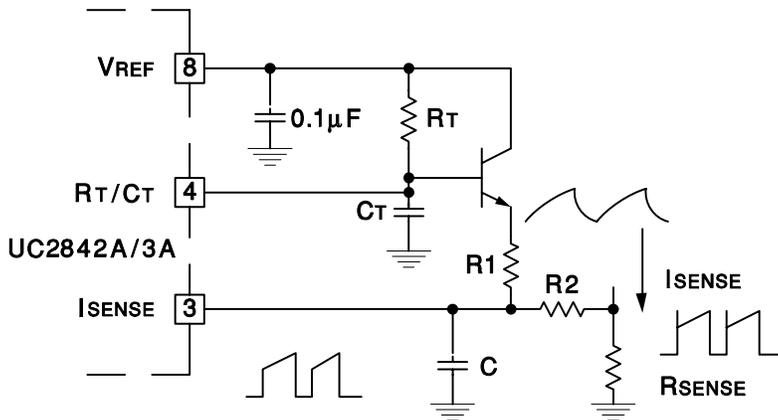
A fraction of the oscillator ramp can be resistively summed with the current sense signal to provide slope compensation for converters requiring duty cycles over 50%.
Note that capacitor, C, forms a filter with R2 to suppress the leading edge switch spikes.

Figure 8. Slope Complression

APPLICATION INFORMATION

Power Supply Specifications

1. Input Voltage   95VAC to 130VAC (50Hz/60Hz)
2. Line Isolation   3750V
3. Switching Frequency   40 kHz
4. Efficiency, Full Load   70%
5. Output Voltage:
    A. +5V, ±5%; 1A to 4A Load
    B. +12V, ±3%; 0.1A to 0.3A Load Ripple voltage: 100 mV P-P Max
    C. −12V, ±3%; 0.1A to 0.3A Load Ripple voltage: 100 mV P-P Max

Figure 9. Off-Line Flyback Regulator

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UC2842AQD8	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(2842AQ, UC2842AQ)	Samples
UC2842AQD8R	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(2842AQ, UC2842AQ)	Samples
UC2842AQDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(2842AQ, UC2842AQ)	Samples
UC2843AQD8	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(2843AQ, UC2843AQ)	Samples
UC2843AQD8R	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(2843AQ, UC2843AQ)	Samples
UC2843AQDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(2843AQ, UC2843AQ)	Samples
UC2845AQD8	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(2845AQ, UC2845AQ)	Samples
UC2845AQD8R	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(2845AQ, UC2845AQ)	Samples
UC2845AQDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(2845AQ, UC2845AQ)	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

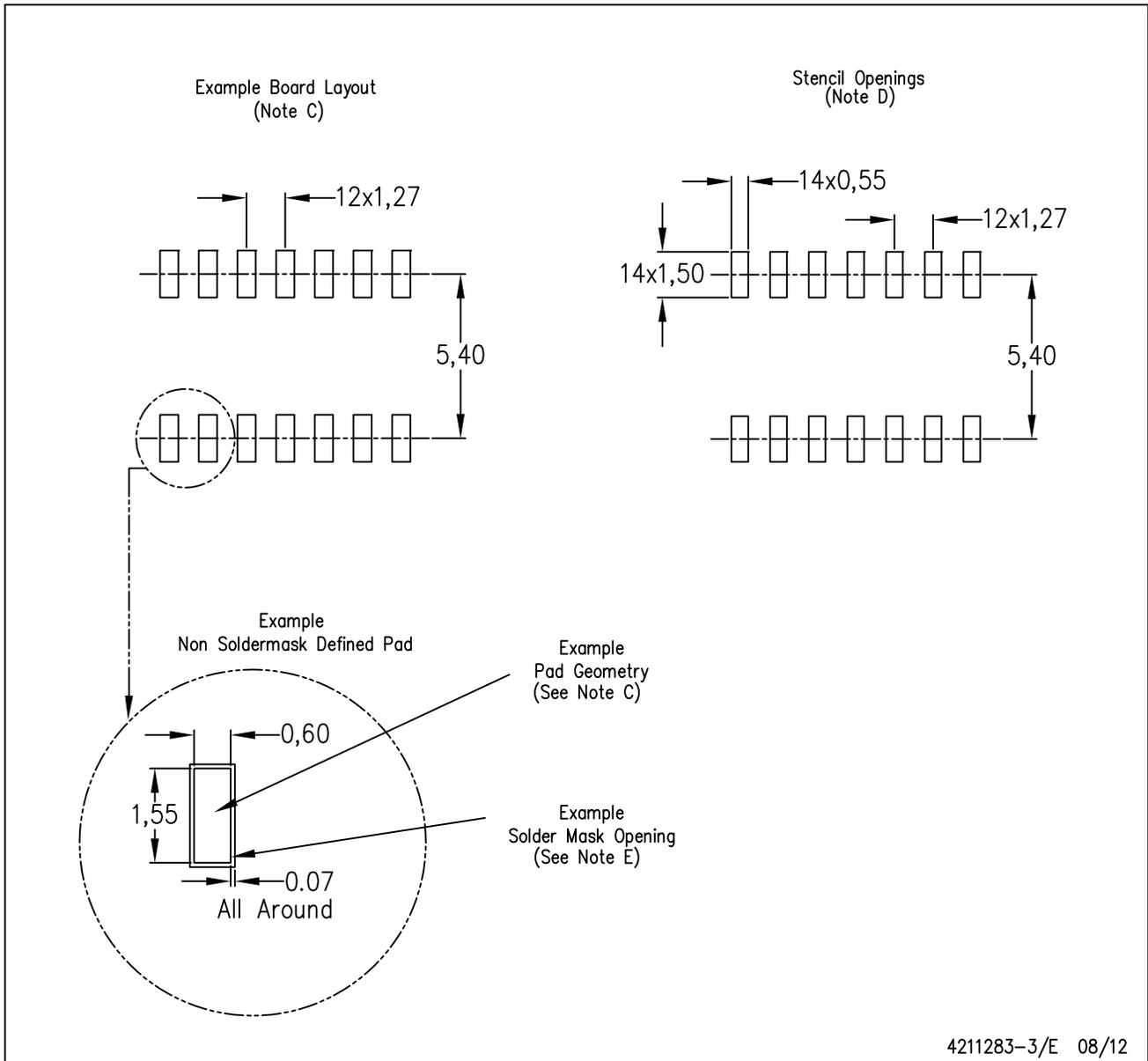| Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2842AQD8R	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UC2842AQDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
UC2843AQD8R	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UC2843AQDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
UC2845AQD8R	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UC2845AQDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2842AQD8R	SOIC	D	8	2500	853.0	449.0	35.0
UC2842AQDR	SOIC	D	14	2500	853.0	449.0	35.0
UC2843AQD8R	SOIC	D	8	2500	853.0	449.0	35.0
UC2843AQDR	SOIC	D	14	2500	853.0	449.0	35.0
UC2845AQD8R	SOIC	D	8	2500	853.0	449.0	35.0
UC2845AQDR	SOIC	D	14	2500	853.0	449.0	35.0

D (R—PDSO—G14)   PLASTIC SMALL OUTLINE

0.344 (8,75)
0.337 (8,55)
C

14   8

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80) D

1   7

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°–8°

0.050 (1,27)
0.016 (0,40)

4040047-5/M   06/11

NOTES: A. All linear dimensions are in inches (millimeters).
          B. This drawing is subject to change without notice.
          C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
              not exceed 0.006 (0,15) each side.
          D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
          E. Reference JEDEC MS–012 variation AB.

TEXAS INSTRUMENTS
www.ti.com

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

12x1,27

5,40

Stencil Openings
(Note D)

14x0,55

14x1,50

12x1,27

5,40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

1,55

Example
Solder Mask Opening
(See Note E)

0.07
All Around

4211283−3/E 08/12

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Publication IPC−7351 is recommended for alternate designs.
         D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
             contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
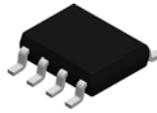
.228-.244   TYP
[5.80-6.19]

A

PIN 1 ID AREA

6X | .050 |
    | [1.27] |

1

8

2X

| .150 |
| [3.81] |

.189-.197
[4.81-5.00]
NOTE 3

4

5

8X .012-.020
[0.31-0.51]

B

.150-.157
[3.81-3.98]
NOTE 4

⊕ | .010 [0.25]Ⓜ | C | A | B |

C

SEATING PLANE

⌒ | .004 [0.1] | C |

4X (0°-15°)

.069 MAX
[1.75]

SEE DETAIL A

4X (0°-15°)

.005-.010   TYP
[0.13-0.25]

| .010 |
| [0.25] |

0° - 8°

.016-.050
[0.41-1.27]

(.041)
[1.04]

.004-.010
[0.11-0.25]

DETAIL A
TYPICAL
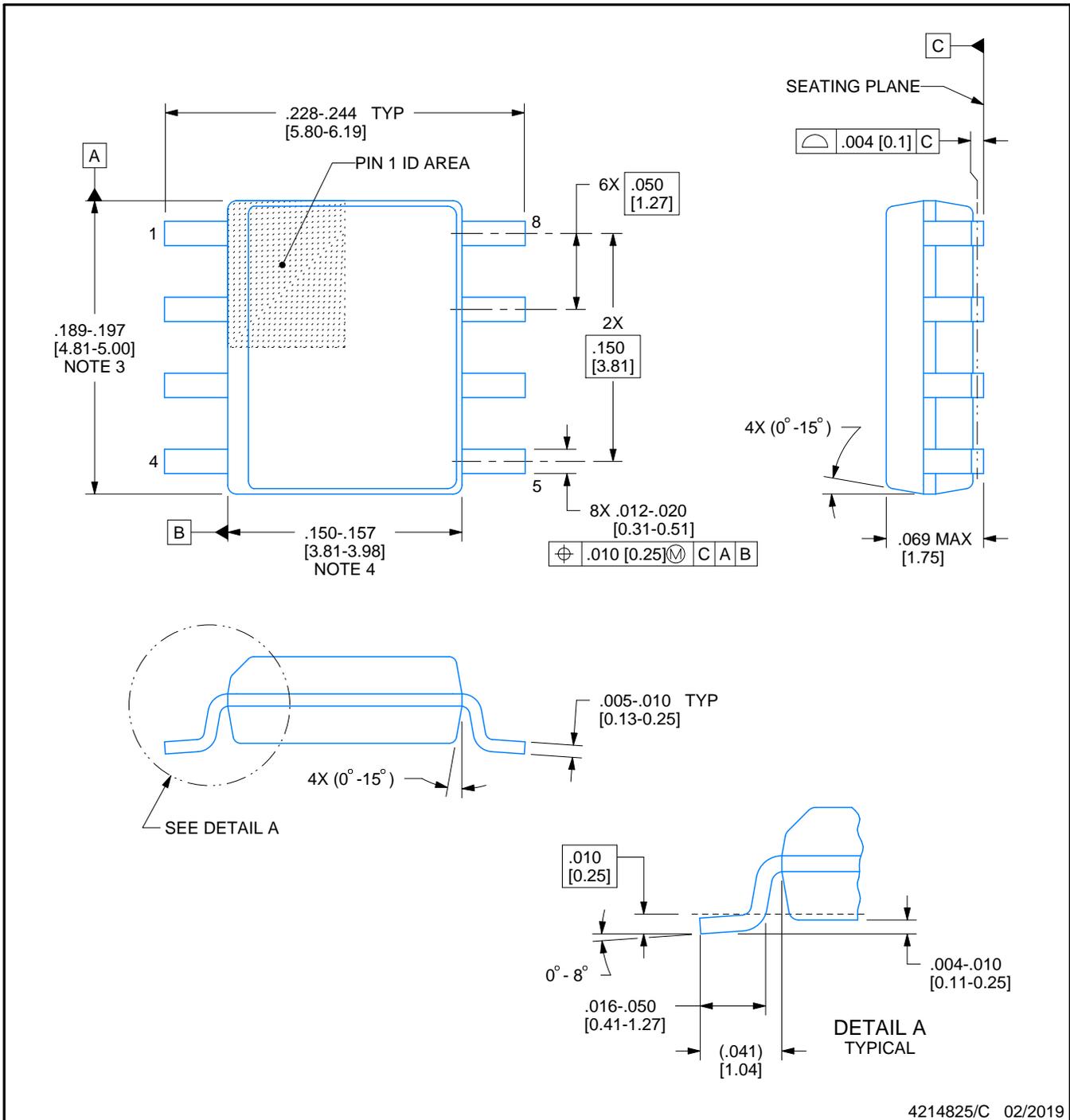
4214825/C   02/2019

NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

8X (.061)
[1.55]

SYMM
₵

SEE
DETAILS

1

8X (.024)
[0.6]

8

SYMM
₵

(R.002) TYP
[0.05]

4

5

6X (.050)
[1.27]

(.213)
[5.4]
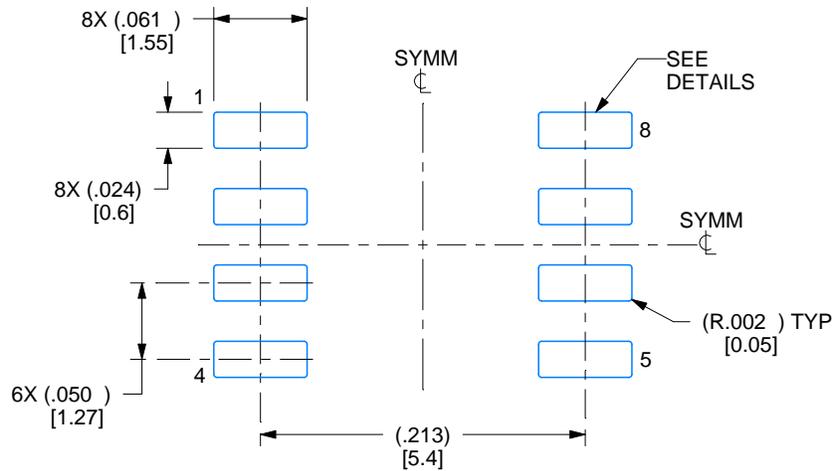
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X

METAL

SOLDER MASK
OPENING

SOLDER MASK
OPENING

METAL UNDER
SOLDER MASK

EXPOSED
METAL

EXPOSED
METAL

.0028 MAX
[0.07]
ALL AROUND

.0028 MIN
[0.07]
ALL AROUND

NON SOLDER MASK
DEFINED

SOLDER MASK
DEFINED
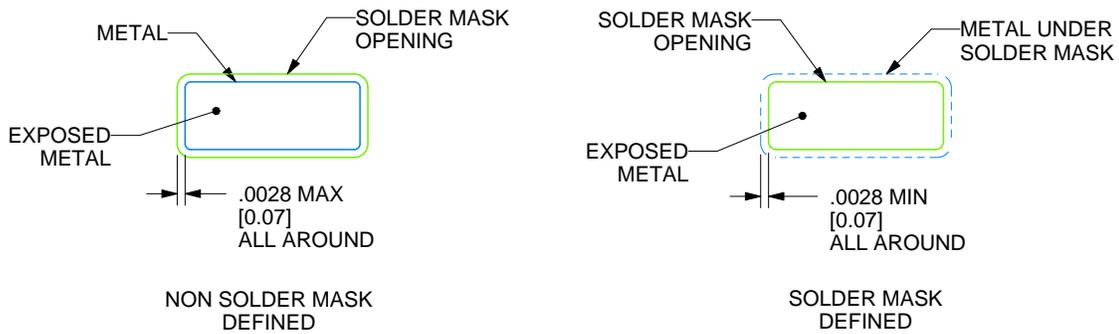
SOLDER MASK DETAILS

4214825/C   02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

8X (.061) [1.55]

8X (.024) [0.6]

6X (.050) [1.27]

SYMM

SYMM

1

4

8

5

(R.002) TYP [0.05]

(.213) [5.4]
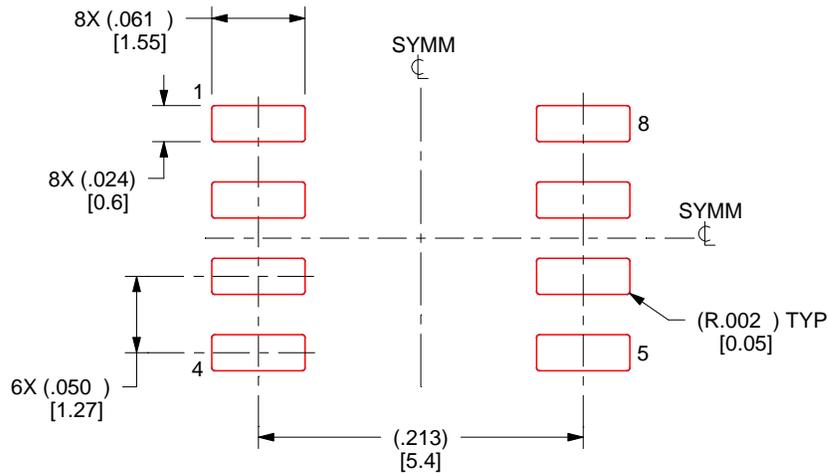
SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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